

[54] INTEGRATED CIRCUIT DEVICE

[75] Inventors: Masahiro Sugimoto, Yokosuka; Hidehiko Akasaki, Kawasaki; Tetsushi Wakabayashi, Yokohama, all of Japan

[73] Assignee: Fujitsu Limited, Kawasaki, Japan

[**] Term: 14 Years

[21] Appl. No.: 397,051

[22] Filed: Jul. 12, 1982

[30] Foreign Application Priority Data

Jan. 14, 1982 [JP] Japan 57-950

[52] U.S. Cl. D13/99; D13/23

[58] Field of Search D13/99; 174/16 HS, 52 FP

[56] References Cited

U.S. PATENT DOCUMENTS

- D. 236,833 9/1975 Beall D13/99
- 2,879,977 3/1959 Trought 174/16 HS
- 3,241,605 3/1966 Tabor 174/16 HS
- 3,808,475 4/1974 Buelow et al. 174/52 FP X
- 3,872,583 3/1975 Beall et al. 174/52 FP X

FOREIGN PATENT DOCUMENTS

2091036 1/1981 United Kingdom 174/52 FP

OTHER PUBLICATIONS

Electronic Design, May 1959, FIG. 1—cutaway of heat exchanger.

IBM Technical Disclosure, vol. 23, No. 9, Feb. 1981, center post heat sink; Nutter et al.

Primary Examiner—Catherine E. Kemper

Assistant Examiner—Clare E. Heflin

Attorney, Agent, or Firm—Staas & Halsey

[57] CLAIM

The ornamental design for an integrated circuit device, as shown.

DESCRIPTION

FIG. 1 is a bottom plan view of an integrated circuit device showing our new design;
 FIG. 2 is a top plan view thereof;
 FIG. 3 is a left side elevational view thereof;
 FIG. 4 is a front elevational view thereof;
 FIG. 5 is a right side elevational view thereof;
 FIG. 6 is a rear elevational view thereof;
 FIG. 7 is a perspective view thereof; and
 FIG. 8 is a sectional view taken along line A—A of FIG. 2.

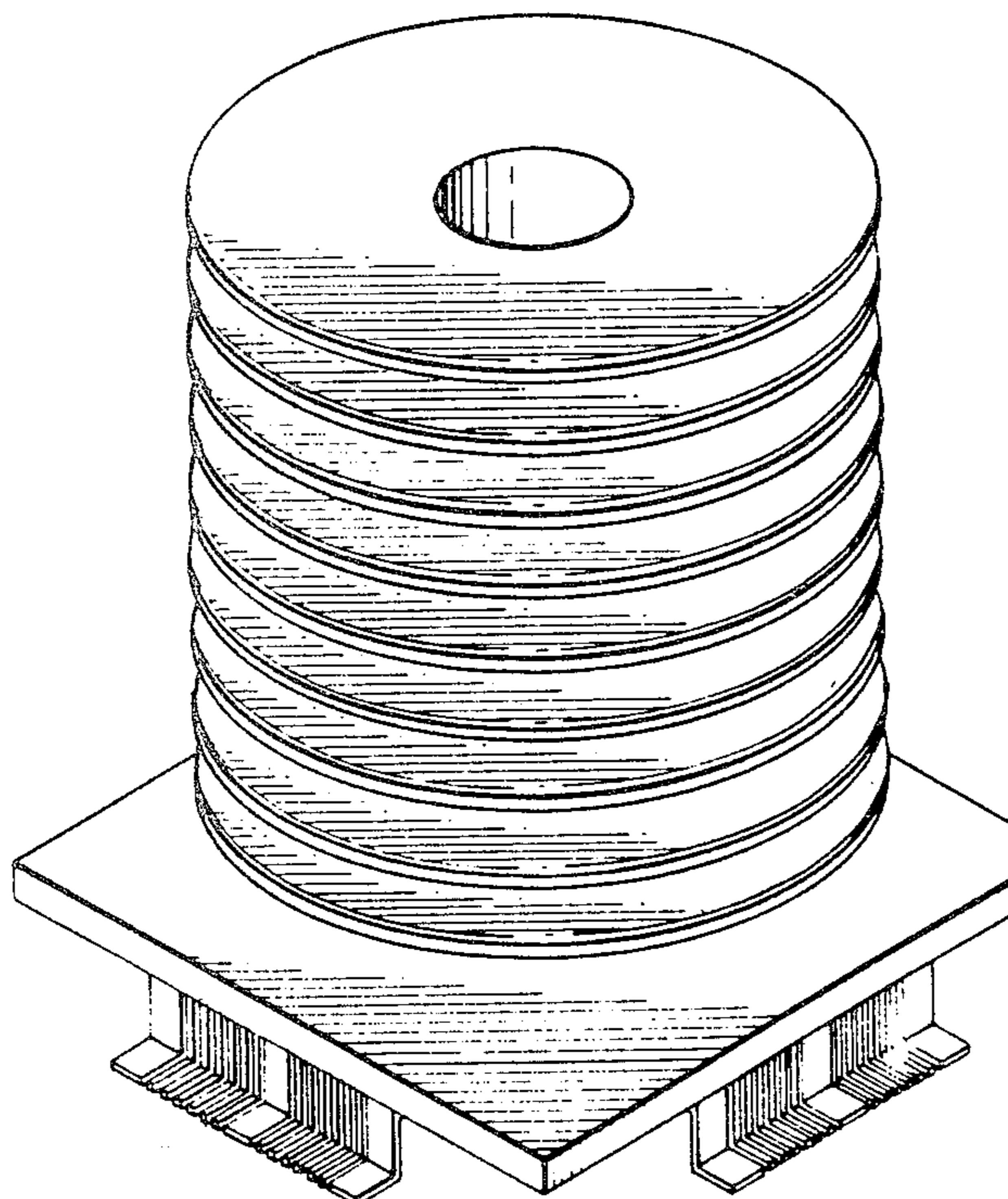


FIG. 1.

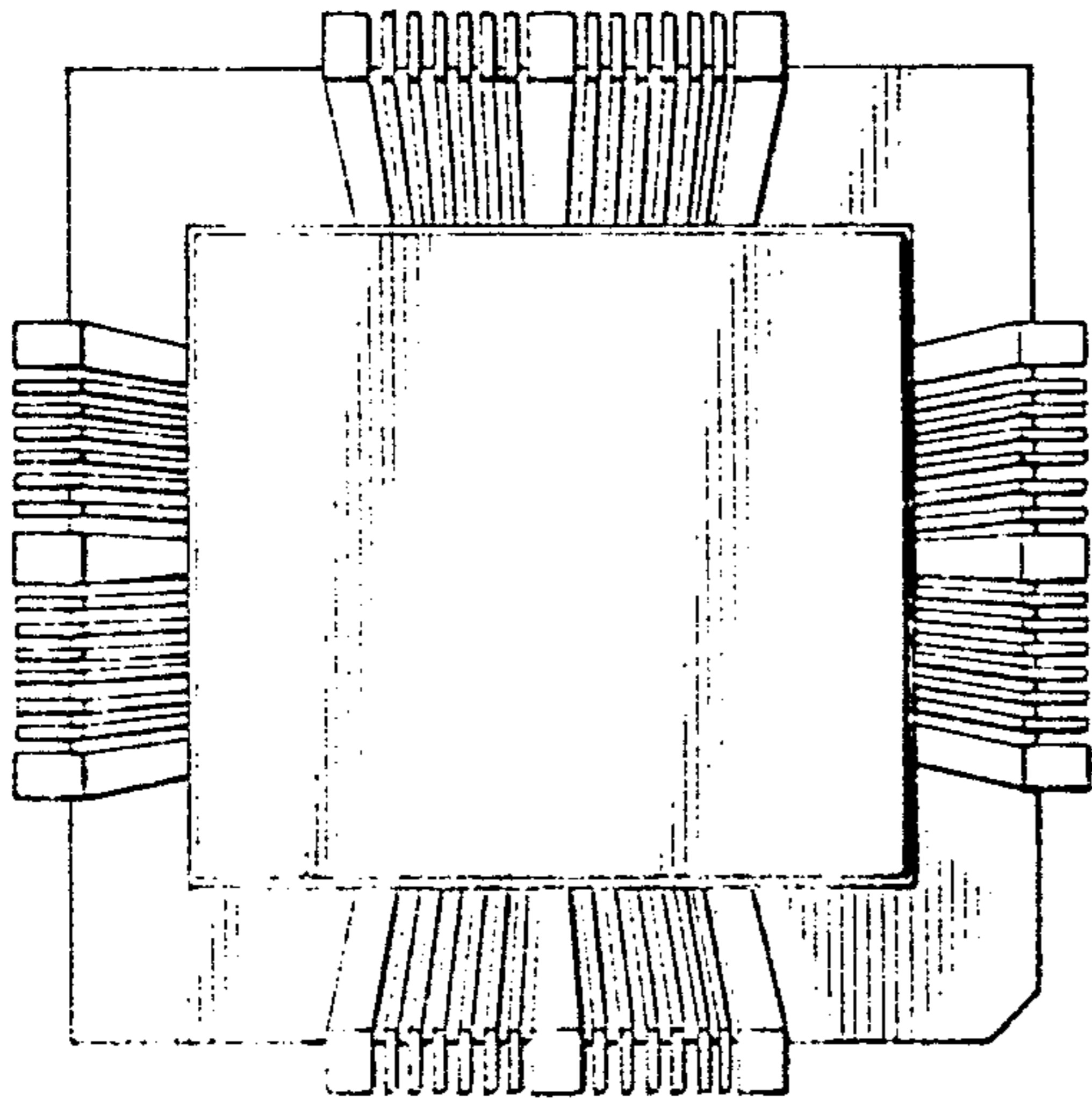


FIG. 2.

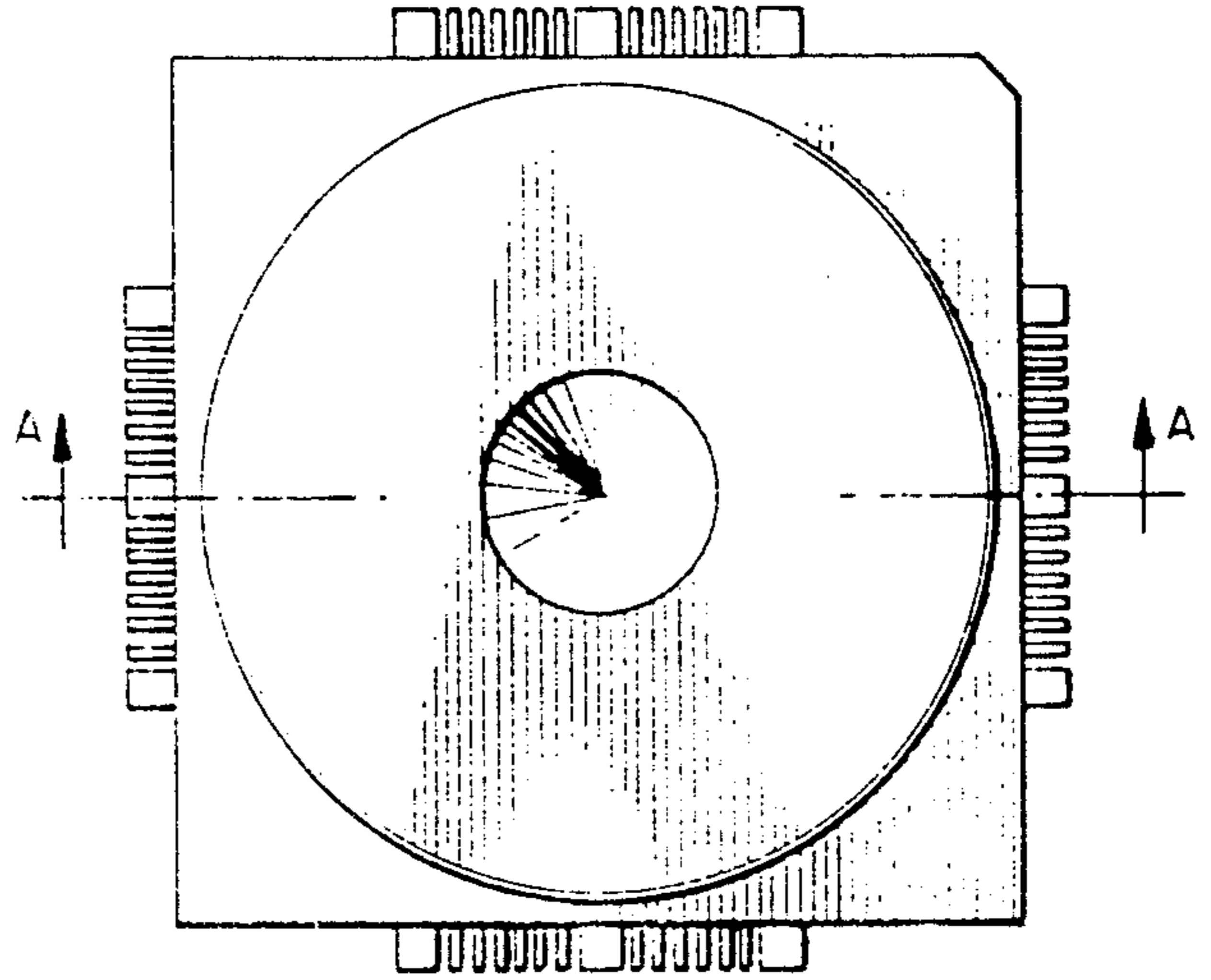


FIG. 3.

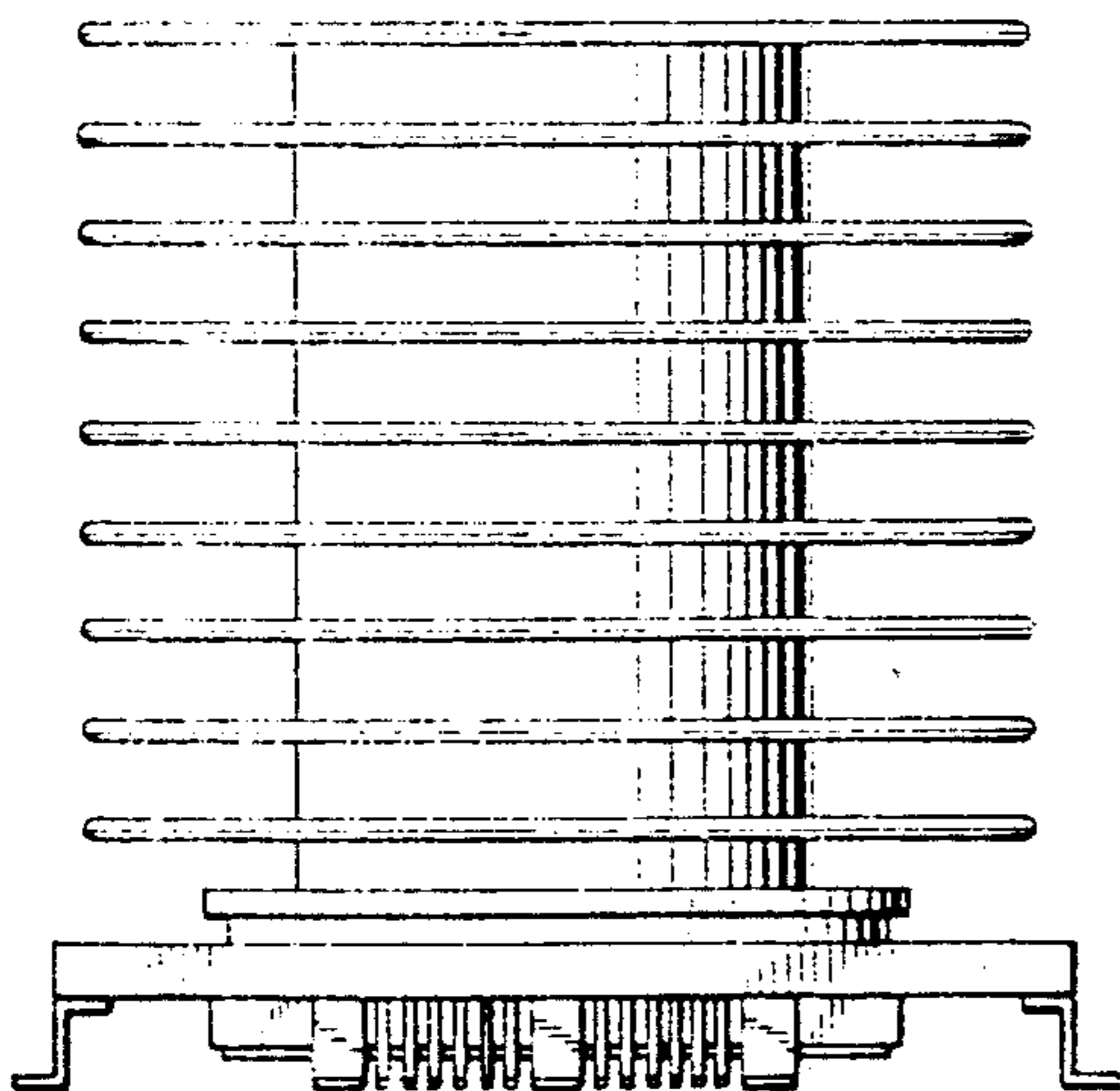


FIG. 4.

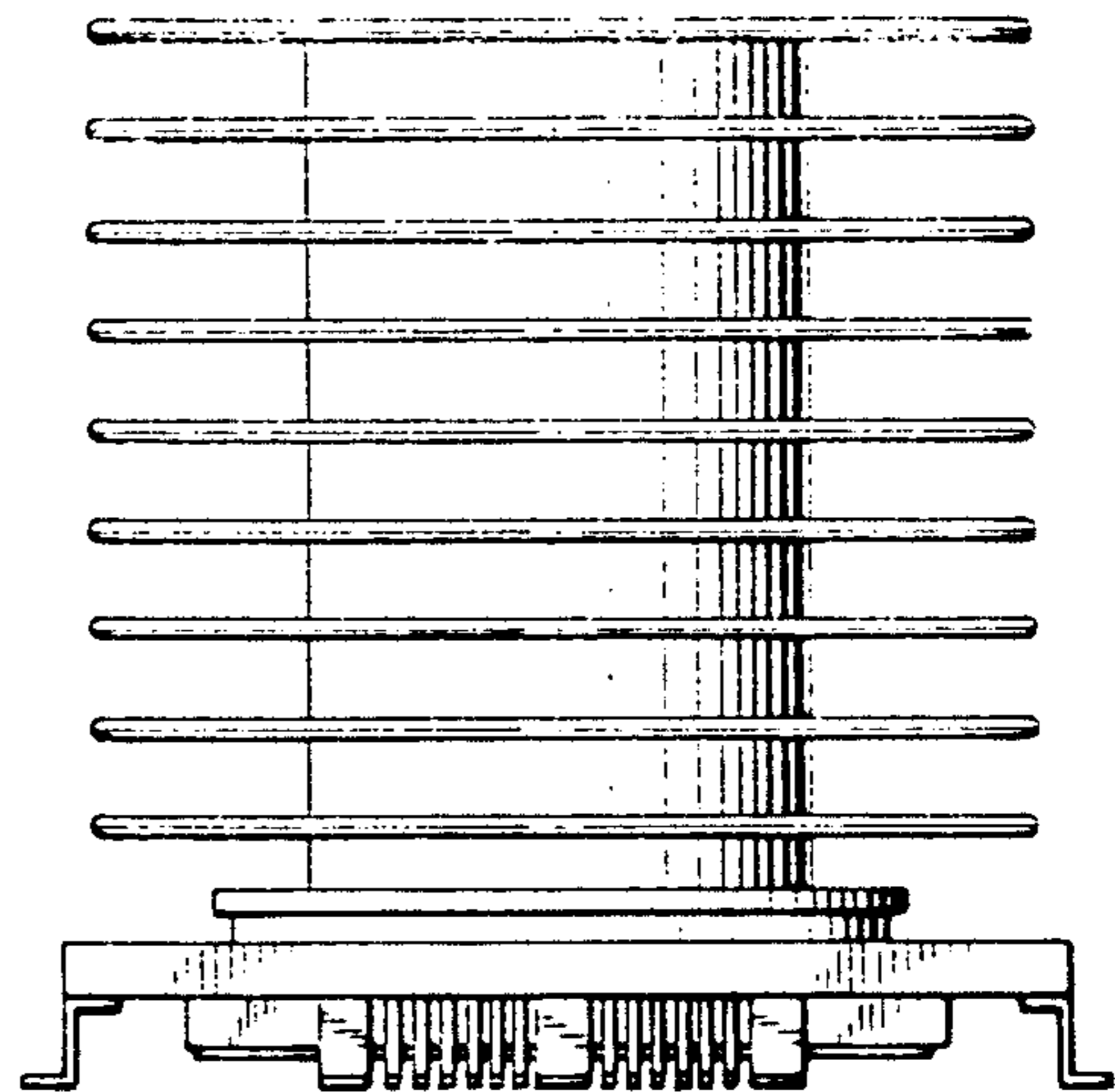


FIG. 7

